

ZESTRON® SD 300

Cleaning medium for the removal of solder pastes, SMT adhesives and thick film pastes from stencils and screens



ZESTRON® SD 300 is a modified solvent-based cleaning agent used to remove solder pastes, SMT adhesives and thick film pastes from stencils and screens in explosion-proof, spray-in-air systems. This medium is also recommended for cleaning misprinted PCBs and even double-sided, populated circuit boards. The high flash point permits manual use as well as the application in printers and stencil cleaning equipment.

Areas of application: Stencil and misprint cleaning		Additional product information:
Solder paste (unsoldered)	++	Technical Information 2: Overview of all fluxes and solder pastes tested Technical Information 3: Material compatibility overview Application Recommendation: Specific process parameters for your cleaning trial
SMT or conductive adhesives	++	
Thick film paste	++	
Low solid flux residues	0	
Rosin based flux residues	+	
Water soluble flux residues	0	

++ highly recommended, best results + recommended 0 possible - not recommended

Technical Centers - ① America, ② Europe, ③ Malaysia, ④ North-China, ⑤ South-China Cleaning Process Solutions under Production Floor Conditions



Advantages compared to other cleaners:

- Due to its wide process window, ZESTRON® SD 300 reliably removes solder pastes, SMT adhesives and resistor pastes from stencils and screens as well as flux residues from misprinted assemblies.
- ZESTRON® SD 300 has a high bath loading capability and therefore a very long bath life and low cleaning costs.
- Due to a flash point of 41°C / 106°F, the cleaner can be used without external explosion-protection systems.
- ZESTRON® SD 300 is also recommended for stencil underside wiping in SMT printers.
- Non-halogenated, organic solvent-based cleaning agent.
- Applicable at ambient cleaning temperature.


Please refer to the material compatibility list (Technical Information 3) before cleaning plastics.

ZESTRON® SD 300 is approved by leading international cleaning and screen printing equipment as well as of stencil manufacturers. Written approvals can be obtained from ZESTRON.


Process Steps	1. Cleaning	2. Rinsing	3. Drying
Explosion-proof spray-in-air system	ZESTRON® SD 300	ZESTRON® SD 300	Circulating or compressed air

Technical Data		
Density	(g/ccm) at 20°C/68°C	0.89
Surface tension	(mN/m) at 25°C/77°F	27.0
Boiling range	°C/°F	120 - 150 / 248 - 302
Flash point	°C/°F	41 / 106
pH-value	10g/l H ₂ O	Neutral
Vapor pressure	(mbar) bei 20°C/68°F	6.2
Cleaning temperature	°C/°F	Room temperature
Solubility in water		Soluble
Application concentration	Ready-to-use	Pure
HMIS Rating	Health-Flammability-Reactivity	1 – 2 – 0


PRODUCT FEATURES



Extensively tested and suitable for cleaning of lead-free solder pastes



Product is free of any critical substances according to SIN & SVHC lists



100% compliance with EU guidelines (RoHS 1 & 2, WEEE)

Filter recommendation:

- To further improve the long bath life time for ZESTRON® SD 300 filtration can be recommended.
- For details, please request our “Filter Recommendation” sheet.

Environmental, health and safety regulations:

- ZESTRON® SD 300 is formulated free of any halogenated compounds and is biodegradable.
- Water rinsing is not necessary which results in the elimination of waste water concerns.
- Refer to the MSDS for specific handling precautions and instructions.

Availability/Storage:

- ZESTRON® SD 300 is available in 1l bottles, 5l or 25l containers and 200l drums.
- Store ZESTRON® SD 300 in the original container at a temperature between 5 - 30°C / 41 - 86°F.
- The product has a minimum shelf life of 5 years in factory sealed containers.

Alternative product recommendation:

- For water-based cleaning of stencils we recommend the MPC® based product VIGON® SC 200.